



Product End-of-Life Disassembly Instructions

Product Category: Notebooks and Tablet PCs

Marketing Name / Model

[List multiple models if applicable.]

HP EliteBook 2540p Notebook PC

Name / Model #2

Name / Model #3

Name / Model #4

Name / Model #5

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm Mother board	1
Batteries	All types including standard alkaline and lithium coin or button style batteries battery and RTC battery	2
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries CCFL	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps LCD	1
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB/PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		
External electrical cables and cords		
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	
Components and waste containing asbestos		
Components, parts and materials containing refractory ceramic fibers		
Components, parts and materials containing radioactive substances		

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1 screw driver	philip #1
Description #2 screw driver	T8
Description #3	
Description #4	
Description #5	

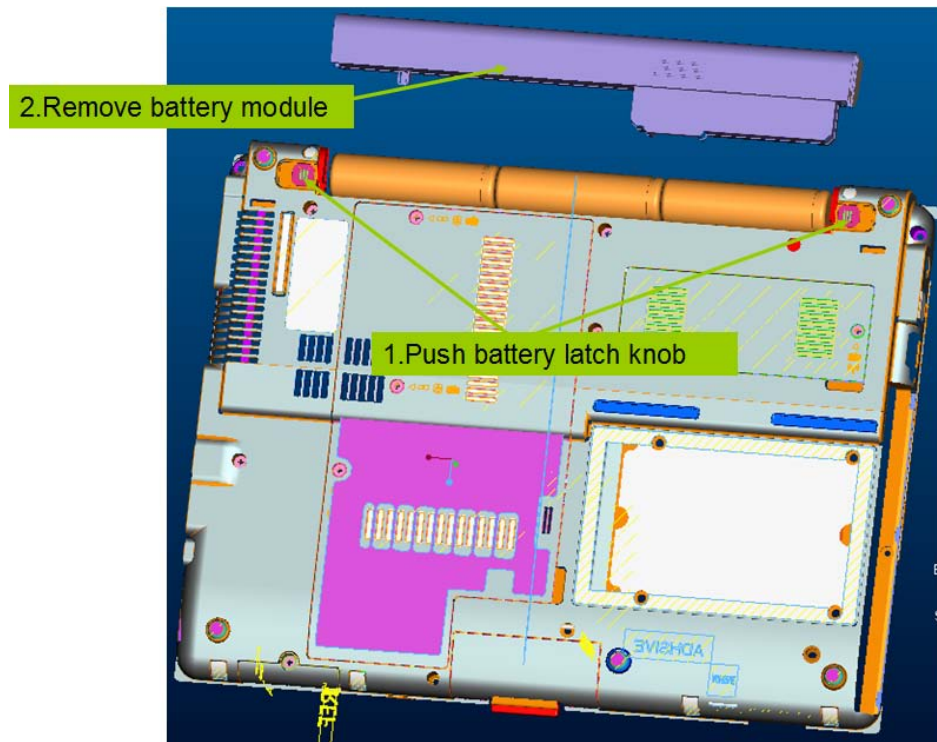
3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

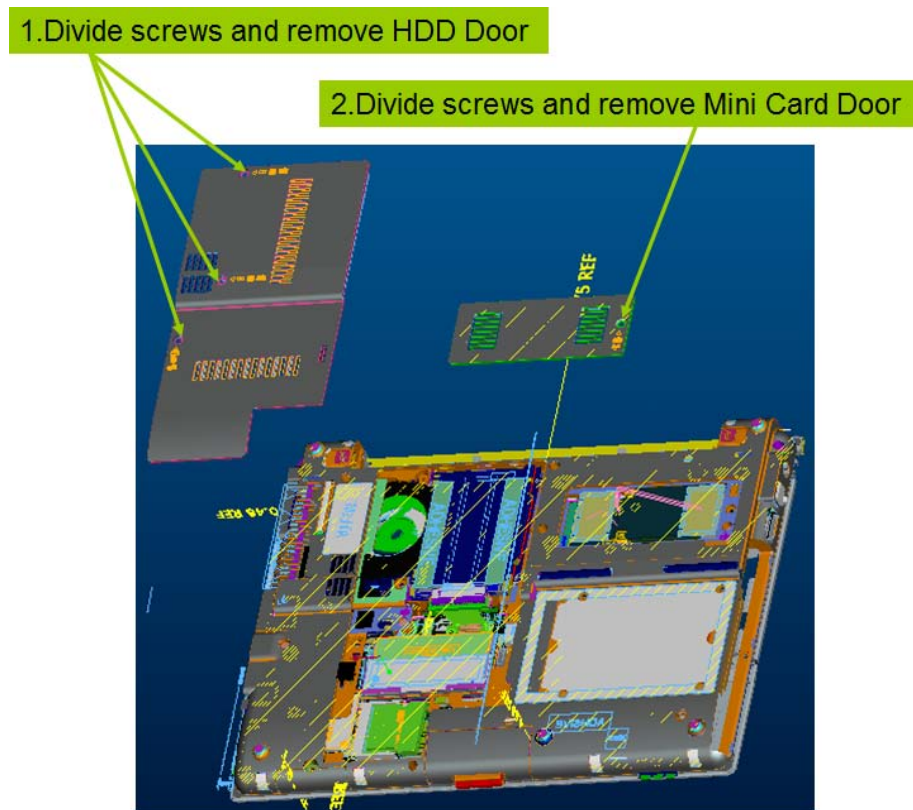
1. Remove Batttery.
2. Remove HDD Door and Mini Card Door.
3. Remove HDD module.
4. Remove Memory card and Mini Card.
5. Remove BT module.
6. Screw to loose.
7. Remove Keyboard module and strip cover module.
8. Remove LCD module.
9. Divide screws.
10. Remove DDR shield.
11. Remove Logic up module.
12. Remove K/B supporter and Smart card module and Touch button module.
13. Remove M/B module.
14. Remove RTC Battery
15. Remove Thermal module.
16. Remove Speaker module.
17. Remove Bezel module.
18. Remove LCD module and Hinge
19. Remove K/B Light module and Antenna cover
20. Remove Antenna module and Sensor PCB and MIC module

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

1.Push battery_latch_knob to remove battery.

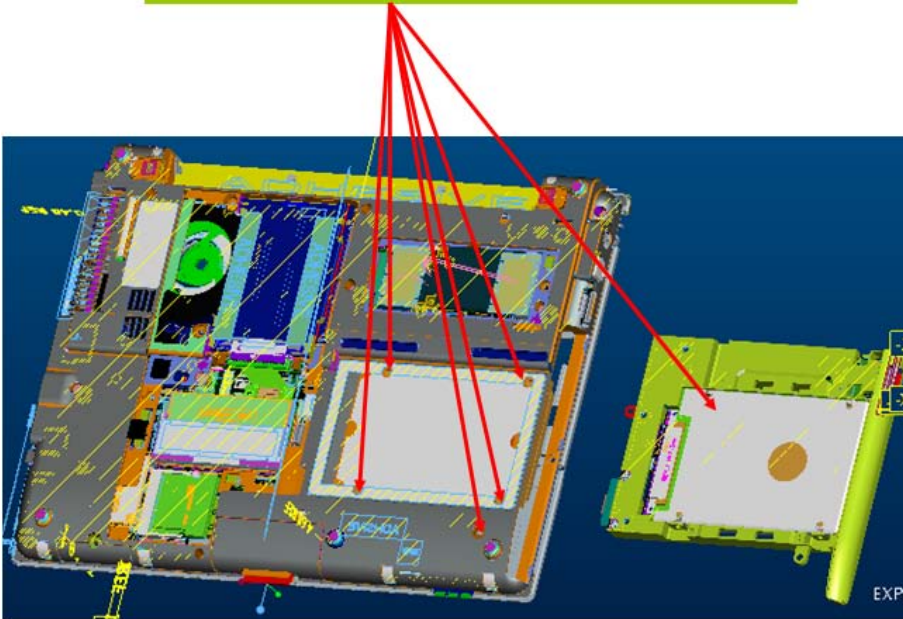


2.Divide the screws to remove the HDD door and Mini card door.



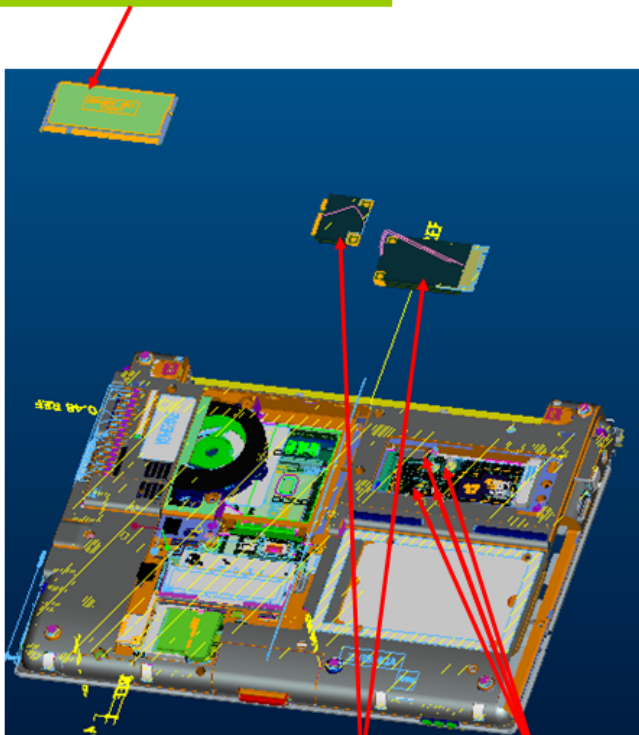
3. Divide the screws to remove HDD module.

1.Divide screws and remove HDD module



4.Remove Memory and two Mini cards

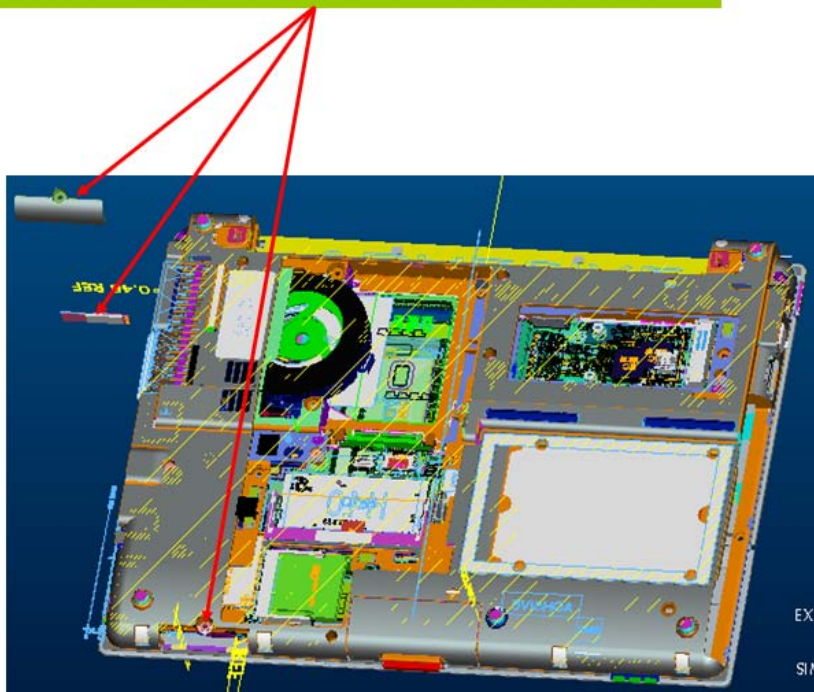
1.Remove Memory card



2.Divide screws and remove Mini card

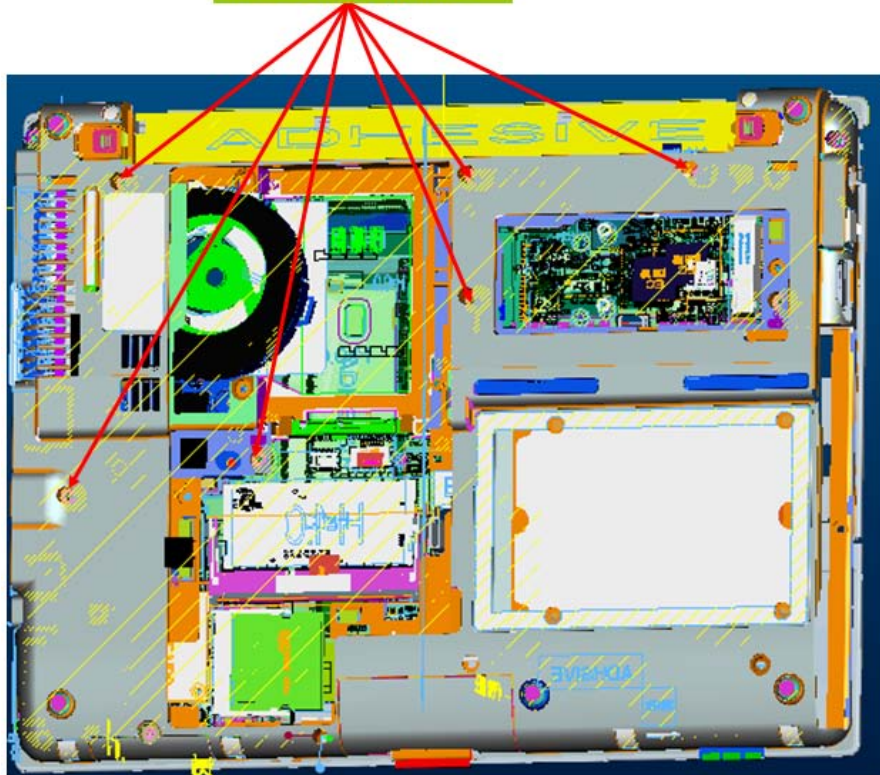
5.Remove BT module

1.Divide screws and remove BT Door and BT module



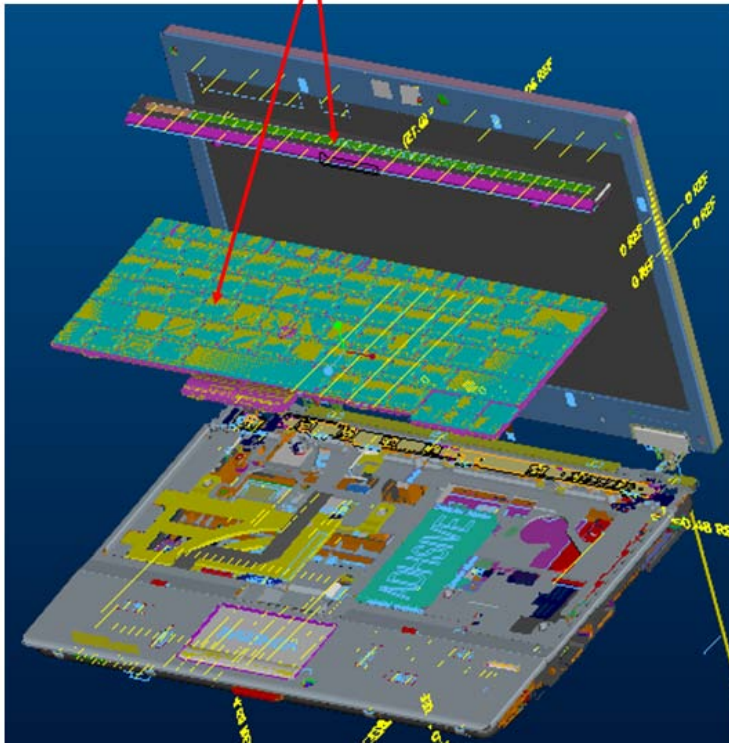
6.Screw to loose

1.Screw to loose



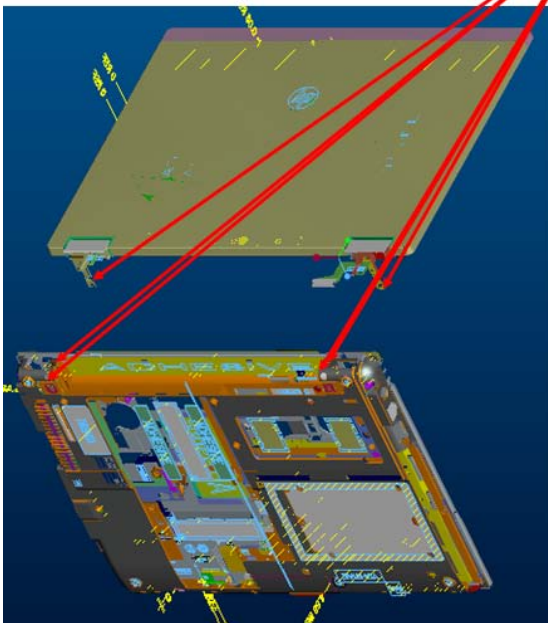
7.Remove Keyboard module and strip cover module

1.Remove Keyboard module and Strip cover module

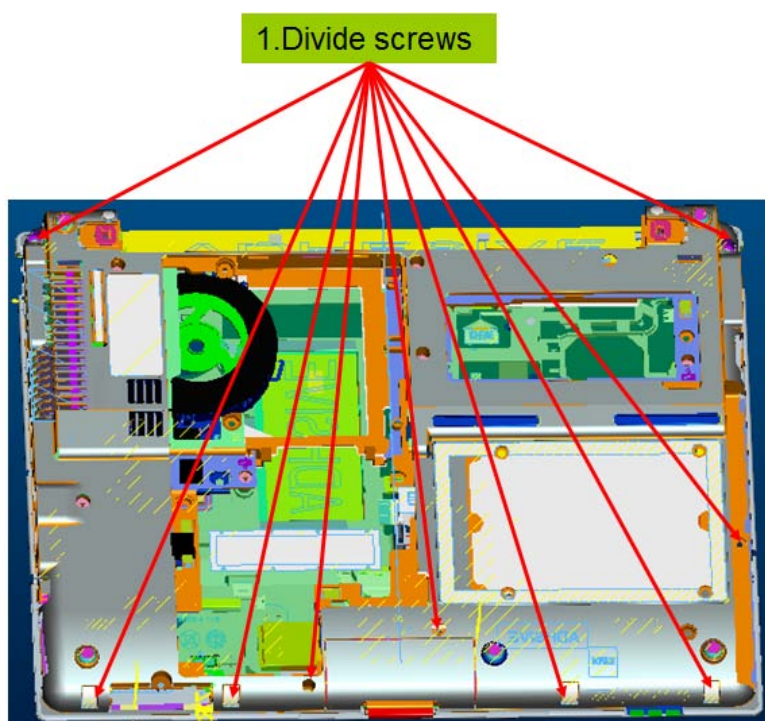


8.Remove LCD module

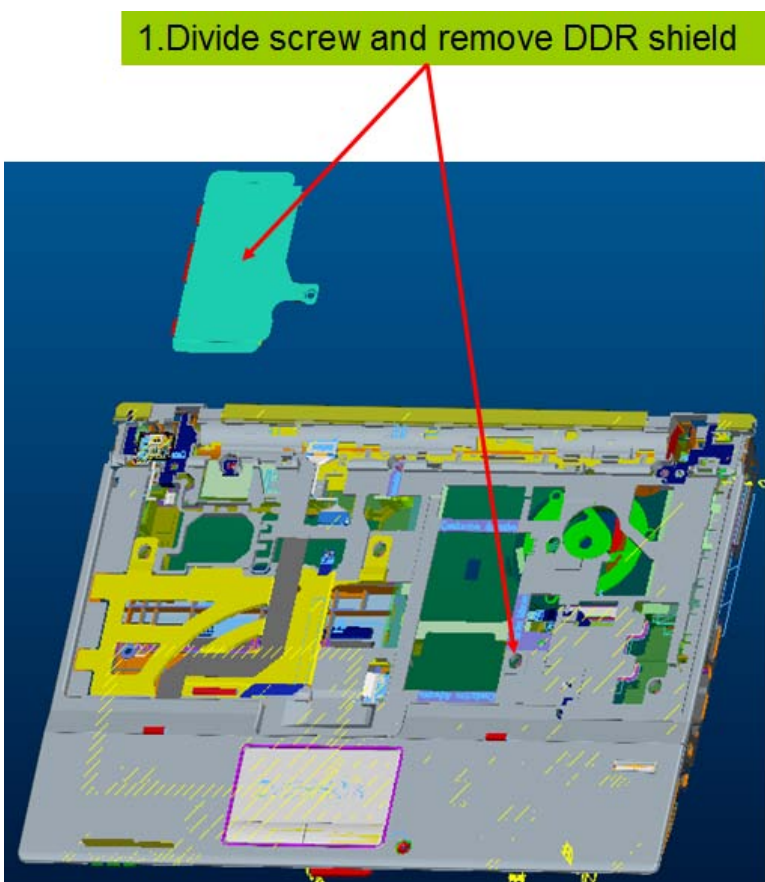
1.Divide screws and remove LCD module



9.Divide screws

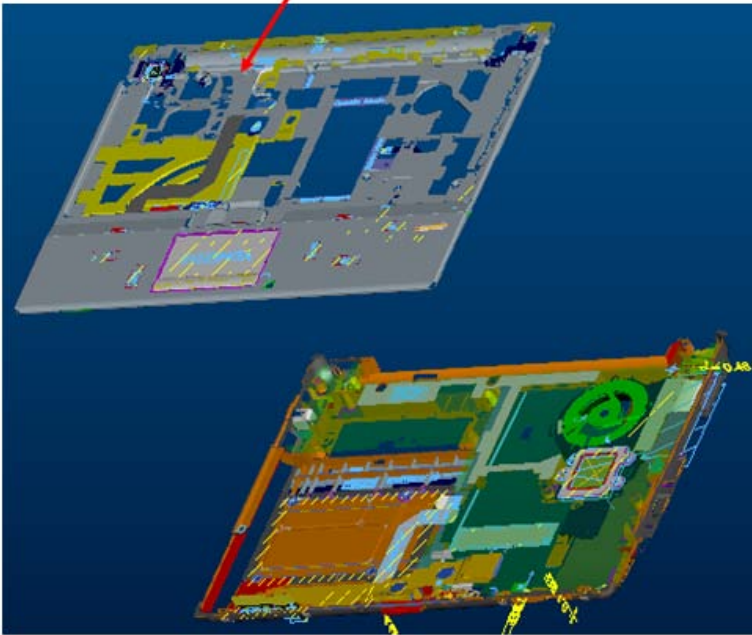


10.Remove DDR shield



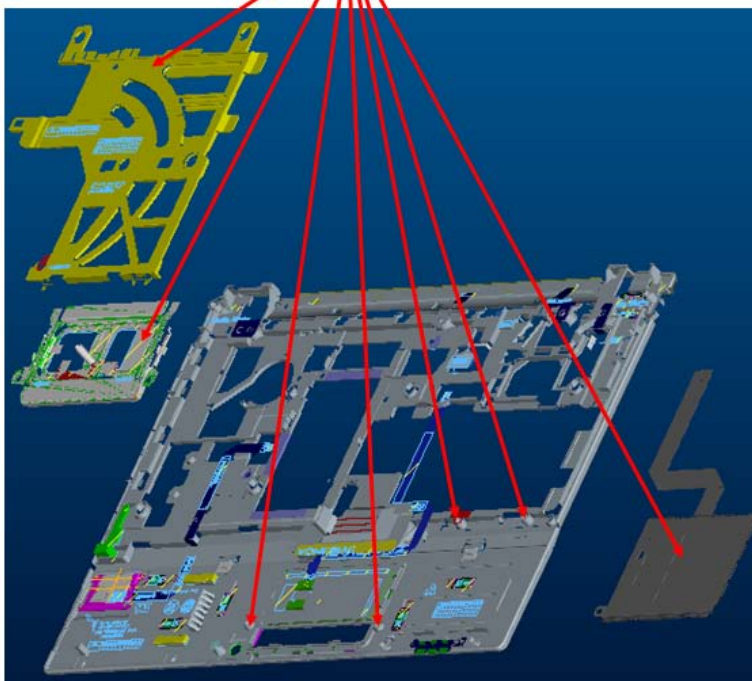
11.Remove Logic up module

1.Remove Logic up module



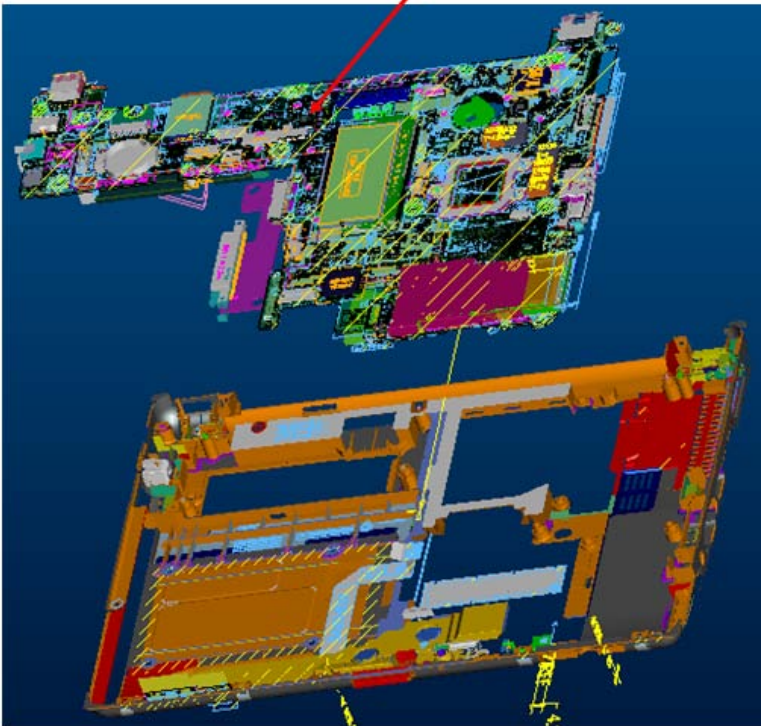
12.Remove K/B supporter and Smart card module and Touch button module

1.Divide screw and remove K/B supporter and Smart card and Touch button



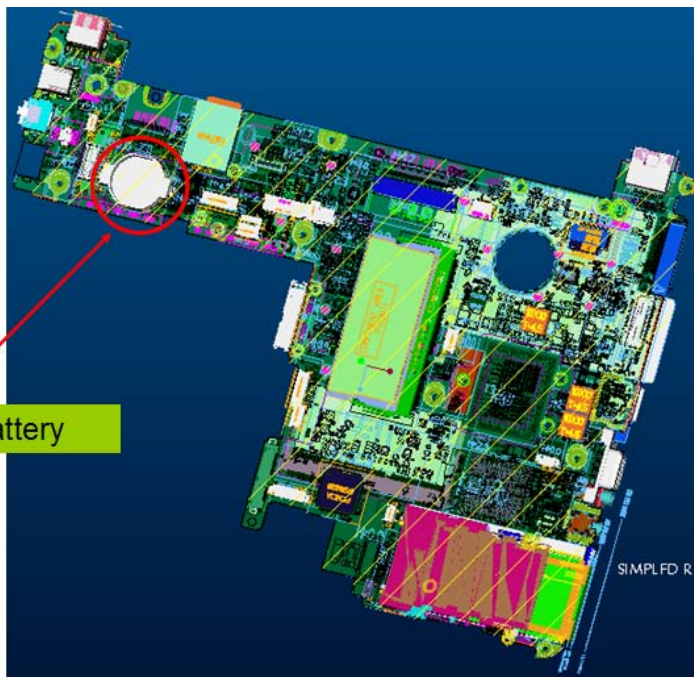
13.Remove M/B module

1.Remove M/B module



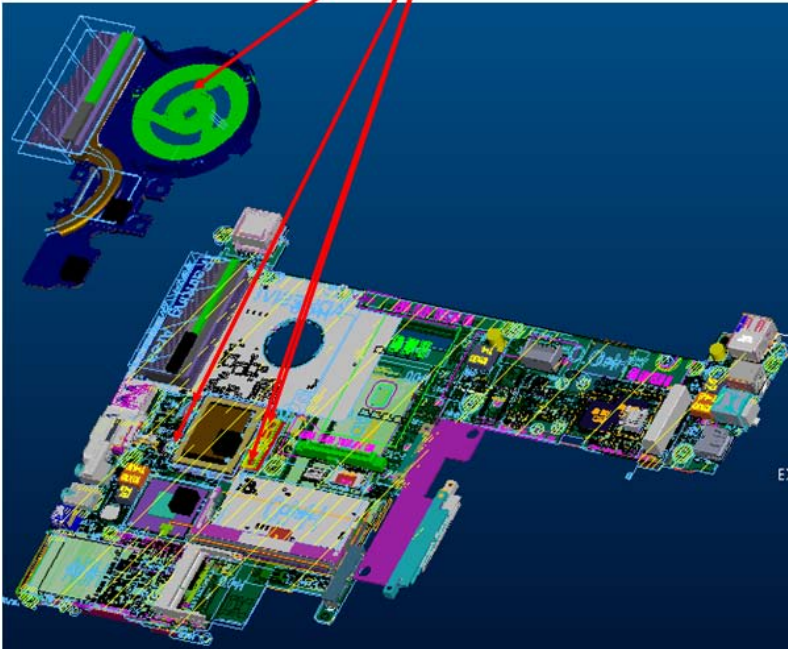
14.Remove RTC Battery

1.Remove RTC Battery



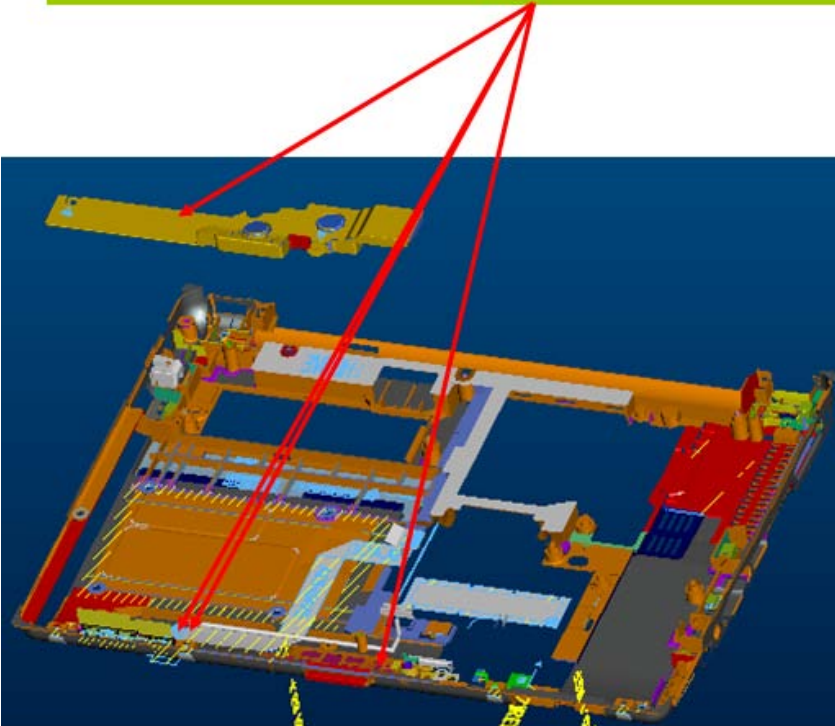
15. Thermal module

1.Divide screws and remove Thermal module



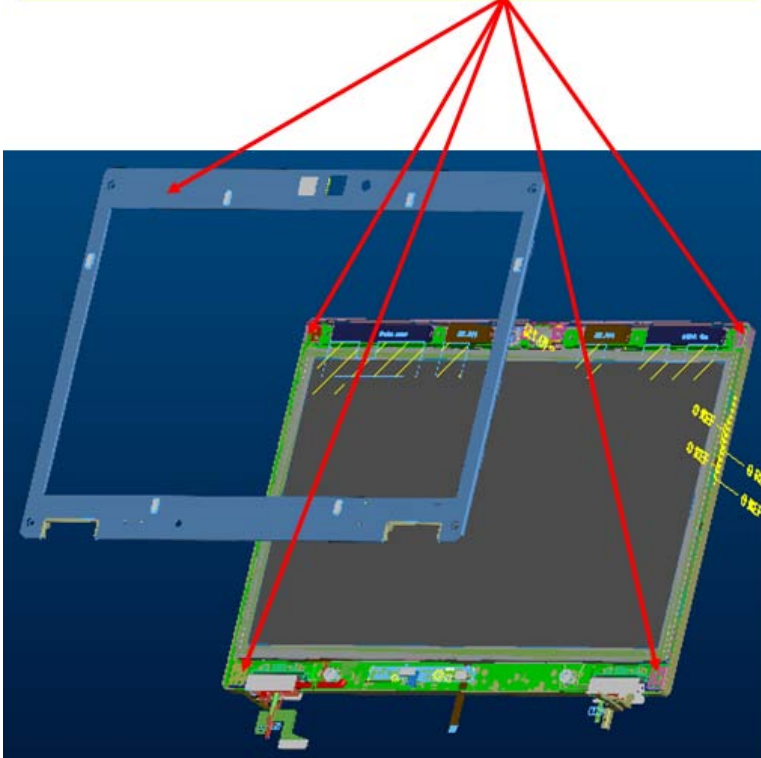
16. Remove Speaker module

1.Divide screws and remove Speaker module



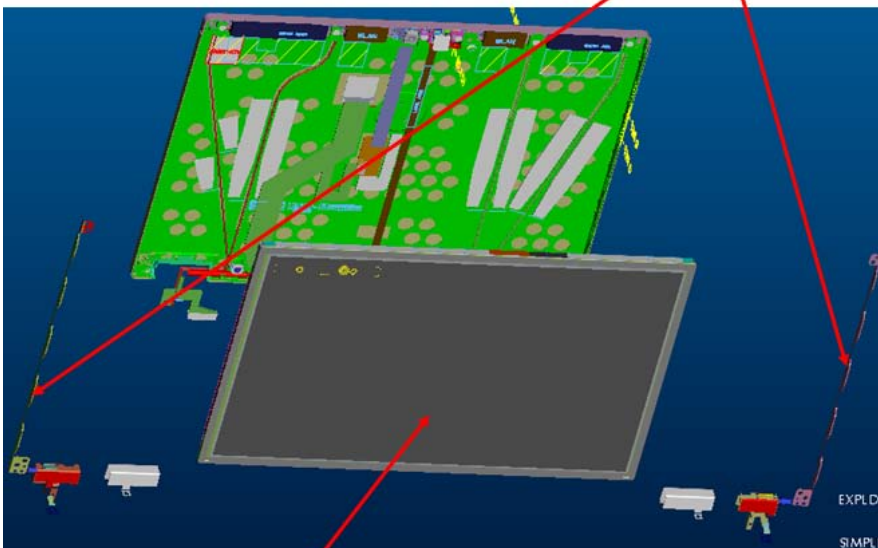
17.Remove Bezel module

1.Divide screws and remove Bezel module



18.Remove LCD module and Hinge

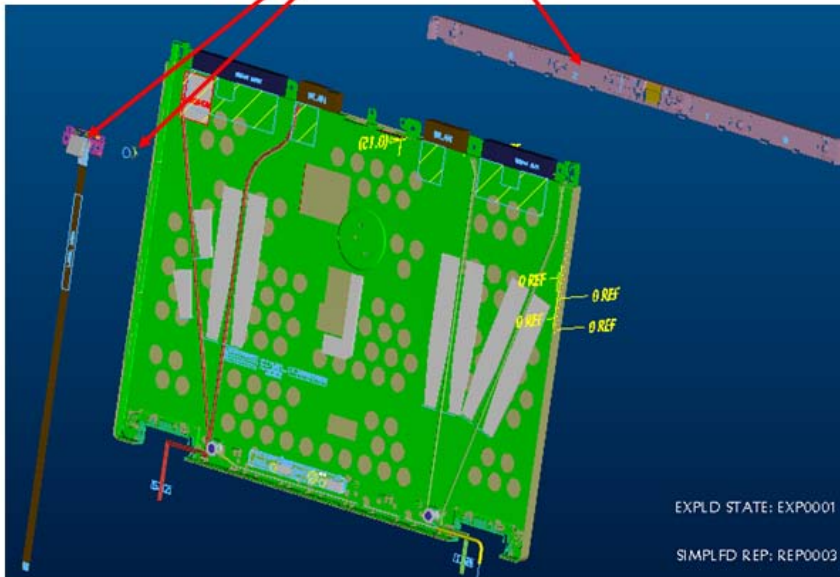
2.Divide screws and remove Hinge



1.Remove LCD module

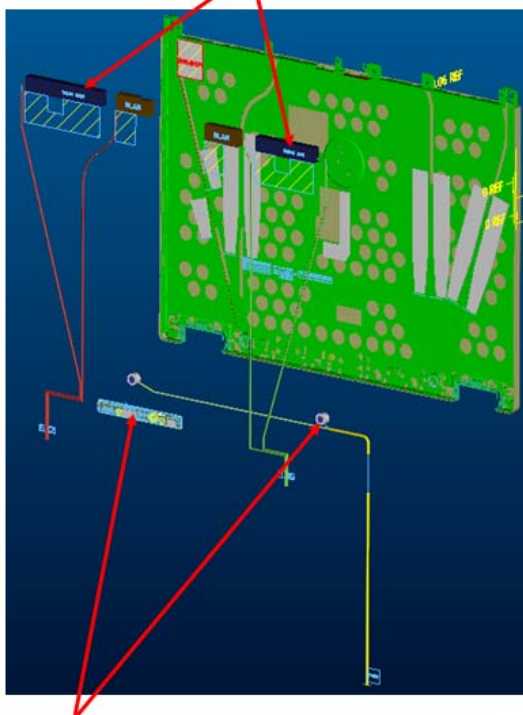
19.Remove K/B Light module and Antenna cover

1.Divide screws and remove K/B Light module and Antenna cover



20.Remove Antenna module and Sensor PCB and MIC module

1.Remove Antenna module



2.Remove Sensor board PCB and MIC module